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- 2-V to 5.5-V V_{CC} Operation
- Support Mixed-Mode Voltage Operation on All Ports
- Fast Switching
- High On-Off Output-Voltage Ratio
- Low Crosstalk Between Switches
- Extremely Low Input Current
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

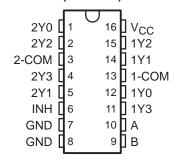
description/ordering information

These dual 4-channel CMOS analog multiplexers/demultiplexers are designed for 2-V to 5.5-V V_{CC} operation.

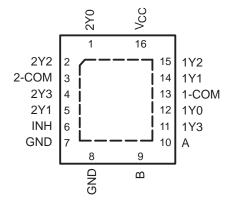
The 'LV4052A devices handle both analog and digital signals. Each channel permits signals with amplitudes up to 5.5 V (peak) to be transmitted in either direction.

Applications include signal gating, chopping, modulation or demodulation (modem), and signal multiplexing for analog-to-digital and digital-to-analog conversion systems.

SN54LV4052A . . . J OR W PACKAGE SN74LV4052A . . . D, DB, DGV, N, NS, OR PW PACKAGE (TOP VIEW)



SN74LV4052A ... RGY PACKAGE (TOP VIEW)



ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N Tube of 25 SN74LV4052AN		SN74LV4052AN	SN74LV4052AN
	QFN – RGY	Reel of 1000	SN74LV4052ARGYR	LW052A
	0010 B	Tube of 40	SN74LV4052AD	11/40504
	SOIC – D	Reel of 2500	SN74LV4052ADR	LV4052A
4000 1- 0500	SOP – NS	Reel of 2000	SN74LV4052ANSR	74LV4052A
–40°C to 85°C	SSOP – DB	Reel of 2000	SN74LV4052ADBR	LW052A
		Tube of 90	SN74LV4052APW	
	TSSOP – PW	Reel of 2000	SN74LV4052APWR	LW052A
		Reel of 250	SN74LV4052APWT	
	TVSOP – DGV	Reel of 2000	SN74LV4052ADGVR	LW052A
–55°C to 125°C	CDIP – J	Tube of 25	SNJ54LV4052AJ	SNJ54LV4052AJ
-55 C to 125°C	CFP – W	Tube of 150	SNJ54LV4052AW	SNJ54LV4052AW

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

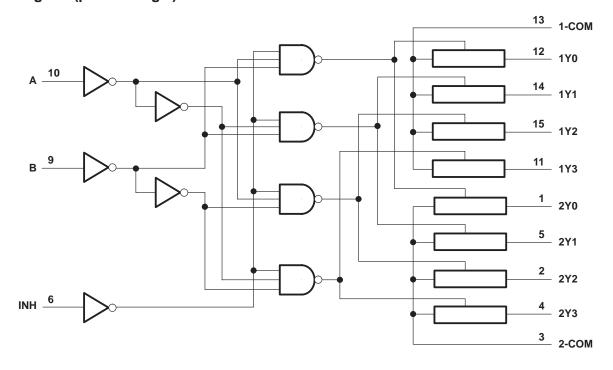


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FUNCTION TABLE

	INPUTS		ON
INH	В	Α	CHANNEL
L	L	L	1Y0, 2Y0
L	L	Н	1Y1, 2Y1
L	Н	L	1Y2, 2Y2
L	Н	Н	1Y3, 2Y3
Н	Χ	Χ	None

logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7.0 V
Input voltage range, V _I (see Note 1)	–0.5 V to 7.0 V
Switch I/O voltage range, V _{IO} (see Notes 1 and 2)	\cdot . -0.5 V to V _{CC} + 0.5 V
Input clamp current, I _{IK} (V _I < 0)	–20 mA
I/O diode current, I _{IOK} (V _{IO} < 0)	–50 mA
Switch through current, I _T (V _{IO} = 0 to V _{CC})	
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ _{JA} (see Note 3): D package	73°C/W
(see Note 3): DB package	82°C/W
(see Note 3): DGV package	120°C/W
(see Note 3): N package	67°C/W
(see Note 3): NS package	64°C/W
(see Note 3): PW package	108°C/W
(see Note 4): RGY package	39°C/W
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 5.5 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.
- 4. The package thermal impedance is calculated in accordance with JESD 51-5.

recommended operating conditions (see Note 5)

			SN54L\	SN54LV4052A		/4052A	LIMIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		2‡	5.5	2‡	5.5	V
		V _{CC} = 2 V	1.5		1.5		
V	High-level input voltage,	V _{CC} = 2.3 V to 2.7 V	V _{CC} ×0.7		V _{CC} ×0.7		.,
VIH	control inputs	V _{CC} = 3 V to 3.6 V	V _{CC} ×0.7		$V_{CC} \times 0.7$		V
		V _{CC} = 4.5 V to 5.5 V	V _{CC} ×0.7	N.	$V_{CC} \times 0.7$		
		V _{CC} = 2 V		0.5		0.5	
.,	Low-level input voltage,	V _{CC} = 2.3 V to 2.7 V	4	$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	V
VIL	control inputs	V _{CC} = 3 V to 3.6 V	, C	V _{CC} ×0.3		$V_{CC} \times 0.3$	V
		V _{CC} = 4.5 V to 5.5 V	20	$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	
٧ı	Control input voltage		0	5.5	0	5.5	V
VIO	Input/output voltage		0	Vcc	0	Vcc	V
		V _{CC} = 2.3 V to 2.7 V		200		200	
Δt/Δν	Input transition rise or fall rate	V _{CC} = 3 V to 3.6 V		100		100	ns/V
		V _{CC} = 4.5 V to 5.5 V		20	·	20	
TA	Operating free-air temperature		- 55	125	-40	85	°C

[‡] With supply voltages at or near 2 V, the analog switch on-state resistance becomes very nonlinear. It is recommended that only digital signals be transmitted at these low supply voltages.

NOTE 5: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			.,	T,	Δ = 25°C	;	SN54LV	4052A	SN74LV	4052A	
	PARAMETER	TEST CONDITIONS	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
		$I_T = 2 \text{ mA},$	2.3 V		43	180		225		225	
ron	On-state switch resistance	V _I = V _{CC} or GND,	3 V		34	150		190		190	Ω
	SWITCH Tesistance	V _{INH} = V _{IL} (see Figure 1)	4.5 V		25	75		100		100	
		I _T = 2 mA,	2.3 V		133	500		600		600	
ron(p)	Peak on-state resistance	$V_I = V_{CC}$ to GND,	3 V		63	180		225		225	Ω
- (1)	On-state resistance	V _{INH} = V _{IL}	4.5 V		35	100		125		125	
	Difference in	I _T = 2 mA,	2.3 V		1.5	30		40		40	
∆ron	on-state resistance	$V_I = V_{CC}$ to GND,	3 V		1.1	20		30		30	Ω
	between switches	VINH = VIL	4.5 V		0.7	15		20		20	
I _I	Control input current	V _I = 5.5 V or GND	0 to 5.5 V			±0.1		±1		±1	μΑ
I _{S(off)}	Off-state switch leakage current	$V_I = V_{CC}$ and $V_O = GND$, or $V_I = GND$ and $V_O = V_{CC}$, $V_{INH} = V_{IH}$ (see Figure 2)	5.5 V			±0.1	Sobucy	±1		±1	μΑ
I _{S(on)}	On-state switch leakage current	V _I = V _{CC} or GND, V _{INH} = V _{IL} (see Figure 3)	5.5 V			±0.1	Q	±1		±1	μΑ
Icc	Supply current	$V_I = V_{CC}$ or GND	5.5 V					20		20	μΑ
C _{IC}	Control input capacitance	f = 10 MHz	3.3 V		2.1						pF
C _{IS}	Common terminal capacitance		3.3 V		13.1						pF
COS	Switch terminal capacitance		3.3 V		5.6						pF
C _F	Feedthrough capacitance		3.3 V		0.5						pF



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switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted)

		FROM	то	TEST	T,	λ = 25°C	;	SN54LV4	052A	SN74LV	4052A	
PAF	RAMETER	(INPUT)	(OUTPUT)	CONDITIONS	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
^t PLH ^t PHL	Propagation delay time	COM or Y	Y or COM	C _L = 15 pF, (see Figure 4)		1.9	10		16		16	ns
^t PZH ^t PZL	Enable delay time	INH	COM or Y	C _L = 15 pF, (see Figure 5)		8	18		23		23	ns
^t PHZ ^t PLZ	Disable delay time	INH	COM or Y	C _L = 15 pF, (see Figure 5)		8.3	18	QQ.	23		23	ns
^t PLH ^t PHL	Propagation delay time	COM or Y	Y or COM	C _L = 50 pF, (see Figure 4)		3.8	12	'Ong	18		18	ns
^t PZH ^t PZL	Enable delay time	INH	COM or Y	C _L = 50 pF, (see Figure 5)		9.4	28	Hd.	35		35	ns
^t PHZ ^t PLZ	Disable delay time	INH	COM or Y	C _L = 50 pF, (see Figure 5)		12.4	28		35		35	ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted)

		FROM	то	TEST	T	λ = 25°C	;	SN54LV4	052A	SN74LV	4052A	
PAR	RAMETER	(INPUT)	(OUTPUT)	CONDITIONS	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
^t PLH ^t PHL	Propagation delay time	COM or Y	Y or COM	C _L = 15 pF, (see Figure 4)		1.2	6		10		10	ns
^t PZH ^t PZL	Enable delay time	INH	COM or Y	C _L = 15 pF, (see Figure 5)		5.7	12		15		15	ns
^t PHZ ^t PLZ	Disable delay time	INH	COM or Y	C _L = 15 pF, (see Figure 5)		6.6	12	"QQ"	15		15	ns
tPLH tPHL	Propagation delay time	COM or Y	Y or COM	C _L = 50 pF, (see Figure 4)		2.5	9	Snac	12		12	ns
^t PZH ^t PZL	Enable delay time	INH	COM or Y	C _L = 50 pF, (see Figure 5)		6.7	20	d _d	25		25	ns
^t PHZ ^t PLZ	Disable delay time	INH	COM or Y	C _L = 50 pF, (see Figure 5)		9.5	20		25		25	ns

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switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted)

DAT	DAMETED.	FROM	то	TEST	T	λ = 25°C	;	SN54LV40	52A	SN74LV	4052A	LINUT
PAI	RAMETER	(INPUT)	(OUTPUT)	CONDITIONS	MIN	TYP	MAX	MIN I	MAX	MIN	MAX	UNIT
^t PLH ^t PHL	Propagation delay time	COM or Y	Y or COM	C _L = 15 pF, (see Figure 4)		0.7	4		7		7	ns
^t PZH ^t PZL	Enable delay time	INH	COM or Y	C _L = 15 pF, (see Figure 5)		4	8		10		10	ns
^t PHZ ^t PLZ	Disable delay time	INH	COM or Y	C _L = 15 pF, (see Figure 5)		5	8	PAG	10		10	ns
^t PLH ^t PHL	Propagation delay time	COM or Y	Y or COM	C _L = 50 pF, (see Figure 4)		1.5	6	Ong	8		8	ns
^t PZH ^t PZL	Enable delay time	INH	COM or Y	C _L = 50 pF, (see Figure 5)		4.7	14	d'd	18		18	ns
^t PHZ ^t PLZ	Disable delay time	INH	COM or Y	C _L = 50 pF, (see Figure 5)		6.9	14		18		18	ns

analog switch characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	FROM	то	TE	ST	Vcc	T,	λ = 25°C	;		
PARAMETER	(INPUT)	(OUTPUT)	UTPUT) CONDITIONS				TYP	MAX	UNIT	
			C _L = 50 pF,	2.3 V		30				
Frequency response (switch on)	COM or Y	Y or COM	$R_L = 600 \Omega$, $f_{in} = 1 MHz$ (sine	e wave)	3 V		35		MHz	
(evilleri ell)			(see Note 6 and		4.5 V		50			
			C _L = 50 pF,		2.3 V		-45			
Crosstalk (between any switches)	COM or Y	Y or COM	$R_L = 600 \Omega$, $f_{in} = 1 MHz$ (sine	e wave)	3 V		-45		dB	
(` ,		4.5 V		-45			
			C _L = 50 pF,	C _L = 50 pF,			20			
Crosstalk (control input to signal output)	INH	COM or Y	R_L = 600 Ω, f_{in} = 1 MHz (squ	3 V		35		mV		
(control input to digital output)			(see Figure 8)	4.5 V		65				
			C _L = 50 pF,		2.3 V		-45			
Feedthrough attenuation (switch off)	COM or Y	Y or COM	$R_L = 600 \Omega$, $f_{in} = 1 MHz$ (sine	wave)	3 V		-45	-45		
(Gillian Gil)			(see Note 7 and		4.5 V		-45			
				$C_L = 50 \text{ pF},$ $V_I = 2 V_{p-p}$		2.3 V		0.1		
Sine-wave distortion	COM or Y	Y or COM	$R_L = 10 kΩ$, $f_{in} = 1 kHz$	$V_{I} = 2.5 V_{p-p}$	3 V		0.1		%	
			(sine wave) (see Figure 10)	V _I = 4 V _{p-p}	4.5 V		0.1			

NOTES: 6. Adjust f_{in} voltage to obtain 0 dBm at output. Increase f_{in} frequency until dB meter reads –3 dB.

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST COI	TEST CONDITIONS		
C _{pd}	Power dissipation capacitance	$C_L = 50 \text{ pF},$	f = 10 MHz	11.8	pF



^{7.} Adjust fin voltage to obtain 0 dBm at input.

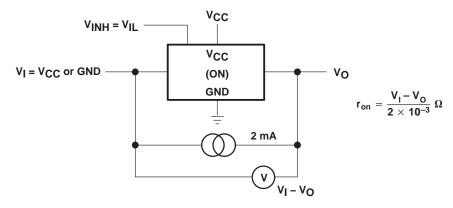
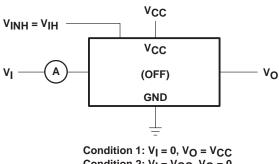


Figure 1. On-State Resistance Test Circuit



Condition 2: $V_I = V_{CC}$, $V_O = 0$

Figure 2. Off-State Switch Leakage-Current Test Circuit

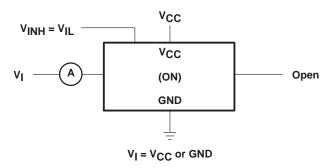


Figure 3. On-State Switch Leakage-Current Test Circuit

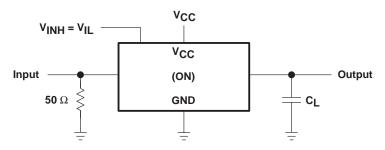


Figure 4. Propagation Delay Time, Signal Input to Signal Output

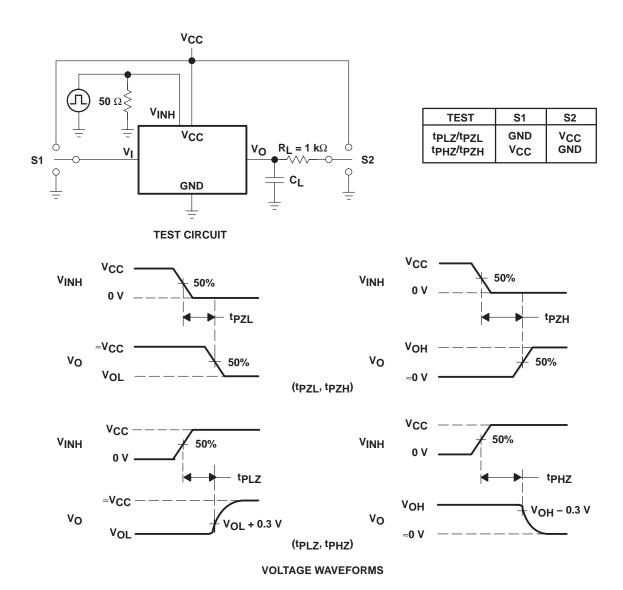
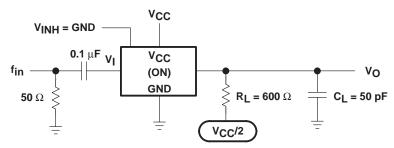


Figure 5. Switching Time (t_{PZL} , t_{PLZ} , t_{PZH} , t_{PHZ}), Control to Signal Output





NOTE A: fin is a sine wave.

Figure 6. Frequency Response (Switch On)

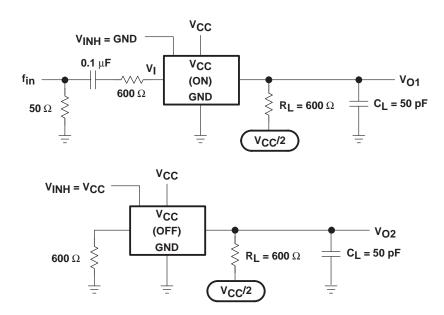


Figure 7. Crosstalk Between Any Two Switches

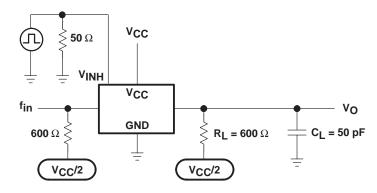


Figure 8. Crosstalk Between Control Input and Switch Output

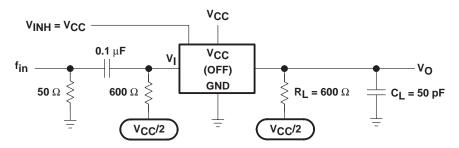


Figure 9. Feedthrough Attenuation (Switch Off)

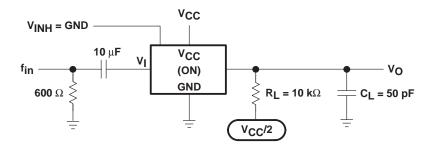


Figure 10. Sine-Wave Distortion







PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LV4052AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV4052ADBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV4052ADBRE4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV4052ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV4052ADGVR	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV4052ADGVRE4	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV4052ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV4052ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV4052AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LV4052ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV4052ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV4052APW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV4052APWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV4052APWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV4052APWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV4052APWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV4052APWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV4052APWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV4052APWTE4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV4052ARGYR	ACTIVE	QFN	RGY	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR

(1) The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

9-Aug-2005

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

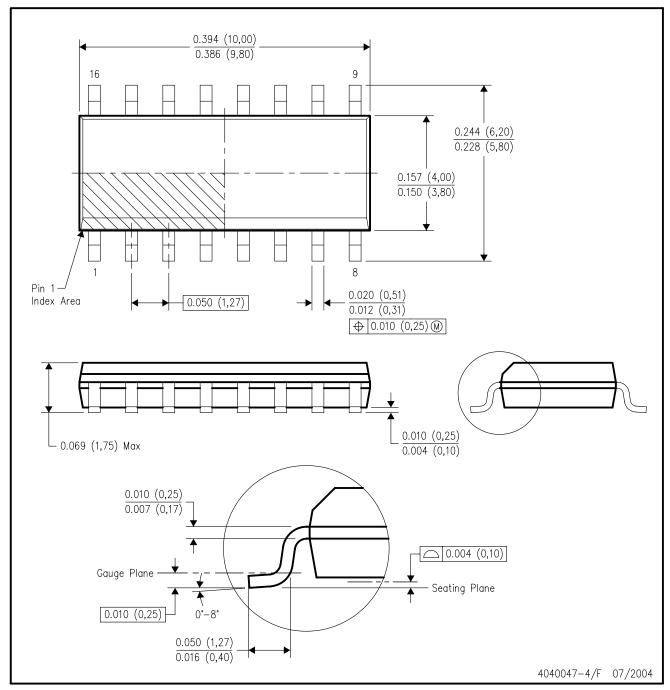
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

D (R-PDSO-G16)

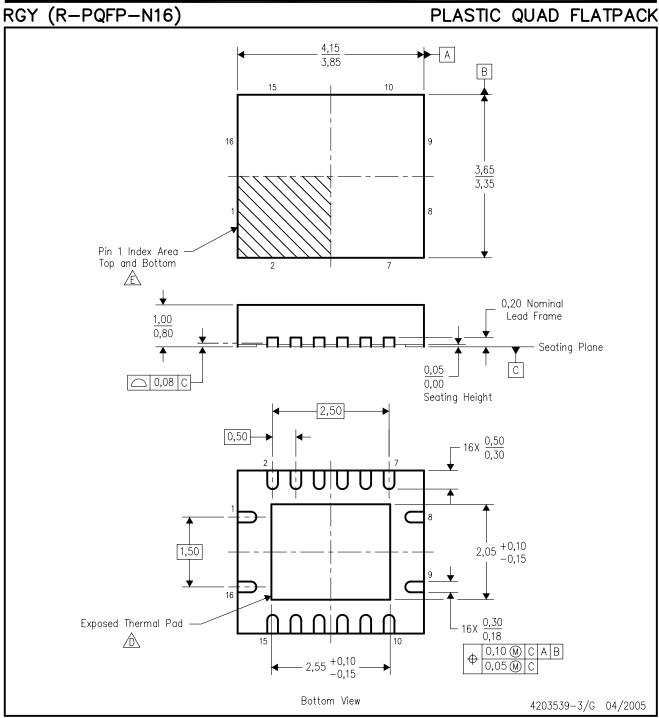
PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.





NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. QFN (Quad Flatpack No-Lead) package configuration.
- The package thermal pad must be soldered to the board for thermal and mechanical performance.
- Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
- F. Package complies to JEDEC MO-241 variation BB.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

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